

AIC1383

1.5A Termination Regulator

FEATURES

- 1.5A Source and Sink Current Ability
- Support DDR1 (1.25V_{TT}) and DDR2 (0.9V_{TT}) Requirements
- Low Output Voltage Offset, ±20mV
- High Accuracy Output Voltage at Full-Load
- Adjustable V_{OUT} by External Resistor
- Low External Component Count
- Current Limit protection
- Thermal Protection
- SOP-8 Package

APPLICATIONS

- Mother Board
- Graphic Cards
- DDR Termination Voltage Supply

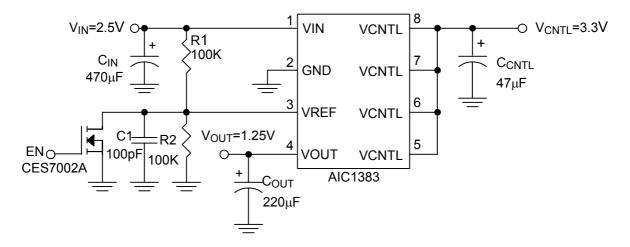
DESCRIPTION

AIC1383 linear regulator is designed to achieve 1.5A source and sink current while regulating an output voltage to within 25mV.

AIC1383 converts voltage supplies range from 1.6V to 6V into an output voltage that adjusts by two external voltage divider resistors. It provides an excellent voltage source for active termination schemes of high-speed transmission lines as those seen in high-speed memory buses, and it meets the JEDEC SSTL-2 and SSTL-3 specifications for termination of DDR-SRAM.

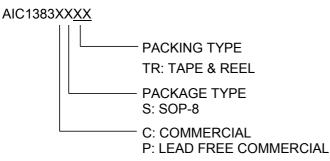
Built-in current limiting in source and sink mode, with thermal shutdown provide maximal protection to the AIC1383 against fault conditions.

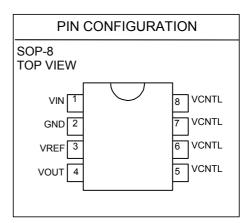






ORDERING INFORMATION





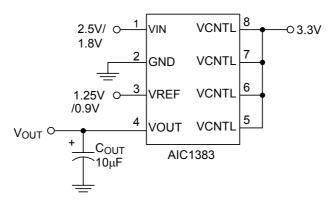
- Example: AIC1383CSTR
 - → 1.5A Version, in SOP-8 Package, Tape & Reel Packing Type AIC1383PSTR
 - → 1.5A Version, in Lead Free SOP-8 Package, Tape & Reel Packing Type

ABSOLUTE MAXIMUM RATINGS

Supply Voltage	-0.4V to 7V			
Operating Temperature Range				
Junction Temperature Range	125°C			
Storage Temperature Range	-65°C ∼150°C			
Lead Temperature (Solder, 10sec)	260°C			
Thermal Resistance θ_{JC} SO-8	40°C /W			
Thermal Resistance $ heta_{JA}$ SO-8	160°C /W			
(Assume no ambient airflow, no heatsink)				

Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

TEST CIRCUIT





ELECTRICAL CHARACTERISTICS (V_{CNTL}=3.3V, V_{IN}=2.5V, V_{REF}=0.5V_{IN},

C_{OUT}=10µF, T_A=25°C, unless otherwise specified) (Note 1)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Input Voltage (DDR1/2)	Keep operate V _{CNTL} ≥V _{IN} at power on and off sequences	V _{IN}	1.6	2.5/1.8		v
		V _{CNTL}	3.0	3.3	6	
Output Voltage	I _{OUT} = 0mA	V _{OUT}		V_{REF}		V
Output Voltage Offset	I _{OUT} = 0mA	V _{os}	-20		20	mV
Load Regulation (DDR1/2)	I _{OUT} =0.1mA ~ +1.5A	ΔV_{LOR}		10	25	mV
	I _{OUT} = 0.1mA ~ -1.5A			10	25	
Quiescent Current	V _{REF} <0.2V, V _{OUT} = OFF	lQ		8	30	μA
Operating Current of V_{CNTL}	No load	I _{CNTL}		3	10	mA
V _{REF} Bias Current	V _{REF} =1.25V				1	μA
Current Limit		١ _{١L}	2.1	3	4.5	А
THERMAL PROTECTION						
Thermal Shutdown Temperature	3.3V≤V _{CNTL} ≤5V	T _{SD}	125	150		°C
Thermal Shutdown Hysteresis	Guaranteed by design			30		°C
SHUTDOWN SPECIFICATIONS						
Shutdown Threshold	Output ON (V _{REF} =0V→1.25V)		0.8			v
	Output OFF (V _{REF} =1.25V→0V)				0.2	

- **Note 1:** Specifications are production tested at T_A=25°C. Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).
- Note 2: V_{OS} is the voltage measurement, which is defined as V_{OUT} subtracted V_{REF} .
- Note 3: Load regulation is measured at constant junction temperature, using pulse testing with a low ON time.
- Note 4: Current limit is measured by pulsing a short time.
- Note 5: For operate system safely; V_{CNTL} must be always greater than $V_{\text{IN}}.$

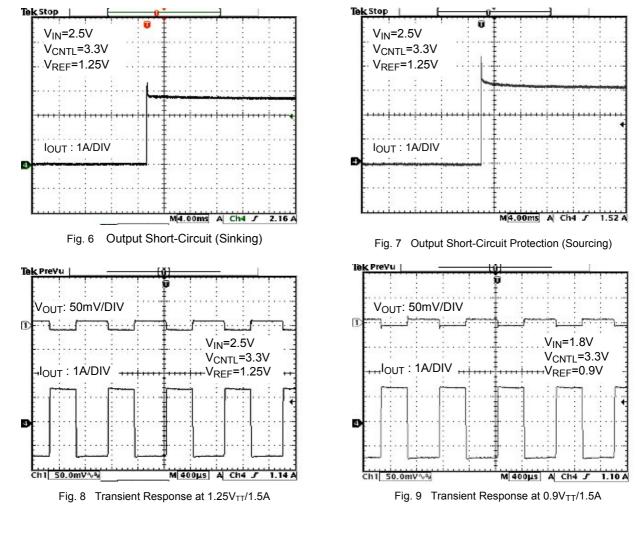
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0.55 0.55 V_{CNTL}=3.3V V_{CNTL}=5V V_{IN}=2.5V 0.50 Threshold Voltage (V) V_{IN}=2.5V Threshold Voltage (V) 0.35 0.35 0.30 -40 0.30 -40 -20 40 100 120 -20 0 20 40 60 80 100 120 0 20 60 80 Temperature (°C) Temperature (°C) Fig. 1 Turn-On Threshold vs. Temp. Fig. 2 Turn-On Threshold vs. Temp 3.0 5 V_{CNTL}=3.3V _VIN=2.5V 2.5 4 VREF=1.25V Output Voltage Offset (mV) Sourcing Current (A) 2.0 No Load 3 1.5 2 1.0 V_{CNTL}=3.3V V_{IN}=2.5V 1 0.5 V_{OUT}=1.25V 0.0 0 60 100 120 -40 -20 0 20 40 80 -40 -20 0 20 40 60 80 100 120 Temperature(°C) Temperature (°C) Fig. 3 Output Voltage Offset vs. Temperature Fig. 4 Current-Limit (Sourcing) vs. Temperature 5 V_{CNTL}=3.3V VIN=2.5V 4 Vout=1.25V Sinking Current (A) 3 2 1 0 L -40 -20 0 40 60 80 100 120 20

TYPICAL PERFORMANCE CHARACTERISTICS

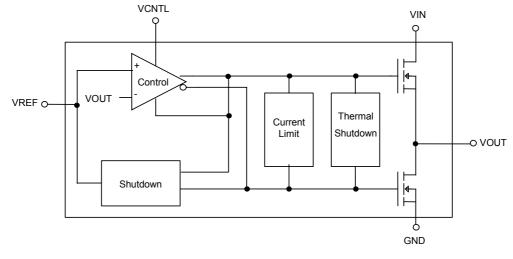
Temperature (°C) Fig. 5 Current-Limit (Sinking) vs. Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)





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PIN DESCRIPTIONS

PIN 1:	VIN	- Input supply pin. It provides
		main power to create the
		external reference voltage by divider resistors for regulating V_{REF} and V_{OUT} .

- PIN 2: GND Ground pin.
- PIN 3: VREF Reference voltage input. Pull this pin low to shutdown device.

APPLICATION INFORMATION

Layout Consideration

AIC1383 is in SOP-8 package resulting in unable to dissipate heat easily when it operates in high current. In order to prevent maximum junction temperature exceeded, the suitable copper area has to use. PIN 4: VOUT - Output pin.

PIN 5~8: VCNTL - Input supply pin. It is used to supply all the internal control circuitry.

The large copper at V_{CNTL} pins is available, and the heat dissipation is relieved. Using via to lead heat into the bottom layer to strengthen as below figures show.

All capacitors should be placed as close as possible to relative pins.

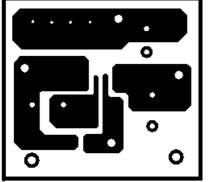


Fig. 10. Top layer

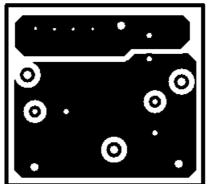


Fig. 11. Bottom layer

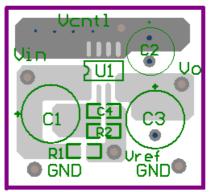
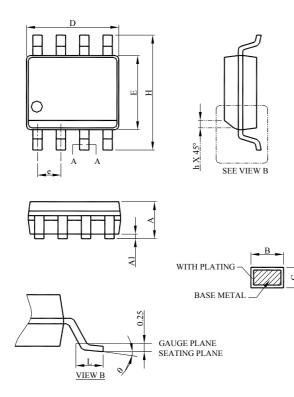


Fig. 12. Placement



PHYSICAL DIMENSIONS (unit: mm)

• SOP-8



s Y	SOI	⊃-8	
S Y B O L	MILLIMETERS		
O L	MIN.	MAX.	
А	1.35	1.75	
A1	0.10	0.25	
В	0.33	0.51	
С	0.19	0.25	
D	4.80	5.00	
E	3.80	4.00	
е	1.27 BSC		
Н	5.80	6.20	
h	0.25	0.50	
L	0.40	1.27	
θ	0°	8°	

Note:

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